



Semiconductor Device Type: RXB-VQFN-32-5x5x0.9mm-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				9.79	100.00%	14.61%		
	Silicon	7440-21-3	9.79		100.00%		14.61%	146119
Plating and Anode Ball				0.89	100.00%	1.33%		
	Lead	7439-92-1	0.00		0.05%		0.00%	7
	Tin	7440-31-5	0.89		99.95%		1.33%	13277
Bond Wire				0.10	100.00%	0.15%		
	Gold	7440-57-5	0.10		100.00%		0.15%	1492
Mold Compound				44.28	100.00%	66.09%		
	Epoxy Resin	Trade Secret	3.10		7.00%		4.63%	46263
	Phenolic Resins	Trade Secret	2.21		5.00%		3.30%	33045
	Silica (Fused)	60676-86-0	33.21		75.00%		49.57%	495672
	Silica	7631-86-9	3.10		7.00%		4.63%	46263
	Metal Hydroxide	Trade Secret	2.21		5.00%		3.30%	33045
	Carbon Black	1333-86-4	0.44		1.00%		0.66%	6609
Die Attach Epoxy				0.88	100.00%	1.31%		
	Silver	7440-22-4	0.60		67.90%		0.89%	8918
	Carbocyclic Acrylate	Trade Secret	0.18		20.00%		0.26%	2627
	Bismaleimide Resin	Trade Secret	0.05		5.50%		0.07%	722
	Acrylate or Acrylic	Trade Secret	0.05		5.50%		0.07%	722
	Epoxy cyclohexylethyltrimethoxysilane	543576	0.00		0.55%		0.01%	72
	Palladium Compound	Trade Secret	0.00		0.55%		0.01%	72
Lead Frame				10.78	100.00%	16.09%		
	Copper	7440-50-8	10.50		97.36%		15.66%	156645
	Iron	7439-89-6	0.26		2.42%		0.39%	3895
	Lead	7439-92-1	0.00		0.01%		0.00%	17
	Phosphorus	7723-14-0	0.01		0.11%		0.02%	169
	Zinc	7440-66-6	0.01		0.11%		0.02%	169
Lead Frame Plating				0.28	100.00%	0.42%		
	Silver	7440-22-4	0.28		100.00%		0.42%	4179
Totals				67.00		100.00%	100.00%	1000000

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